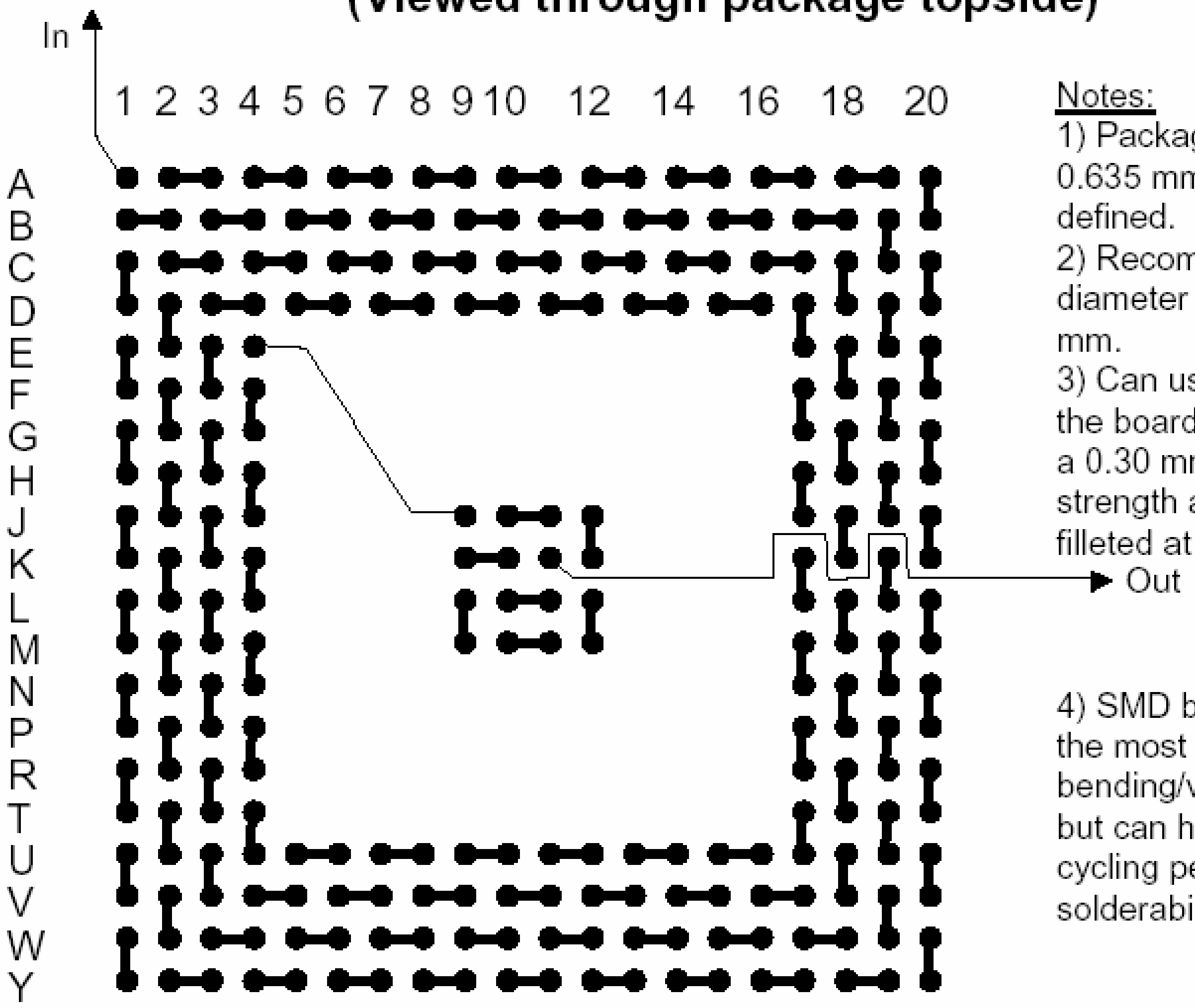
27mm, 272 PBGA Daisy-Chain Test Board Footprint

One Net per package for testing thermal and perimeter balls in series (Viewed through package topside)



Notes:

1) Package pad diameter is 0.635 mm and solder mask defined.

2) Recommend test board pad diameter is from 0.58 to 0.635 mm.

3) Can use NSMD or SMD on the board. NSMD should use a 0.30 mm wide trace for strength and it should be filleted at the pad.

4) SMD board pad will have the most strength and best bending/vibration performance, but can have reduced thermal cycling performance and solderability than NSMD.

27mm, 272 PBGA Daisy-Chain Test Board Footprint

Two Nets per package for testing perimeter and thermal balls independently
(Viewed through package topside)